

## Product End-of-Life Disassembly Instructions

**Product Category: Servers**

**Marketing Name / Model**

[List multiple models if applicable.]

HPE Edgeline EL4000

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Depending on Power Supply Model	3
External electrical cables and cords		
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T10& T15

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System battery: Press the latch of battery holder and pull-out the battery
2. 800 PSU Capacitor remove – See attachment 3 for cap locations.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

**Attachment 1 – System exploding drawing**

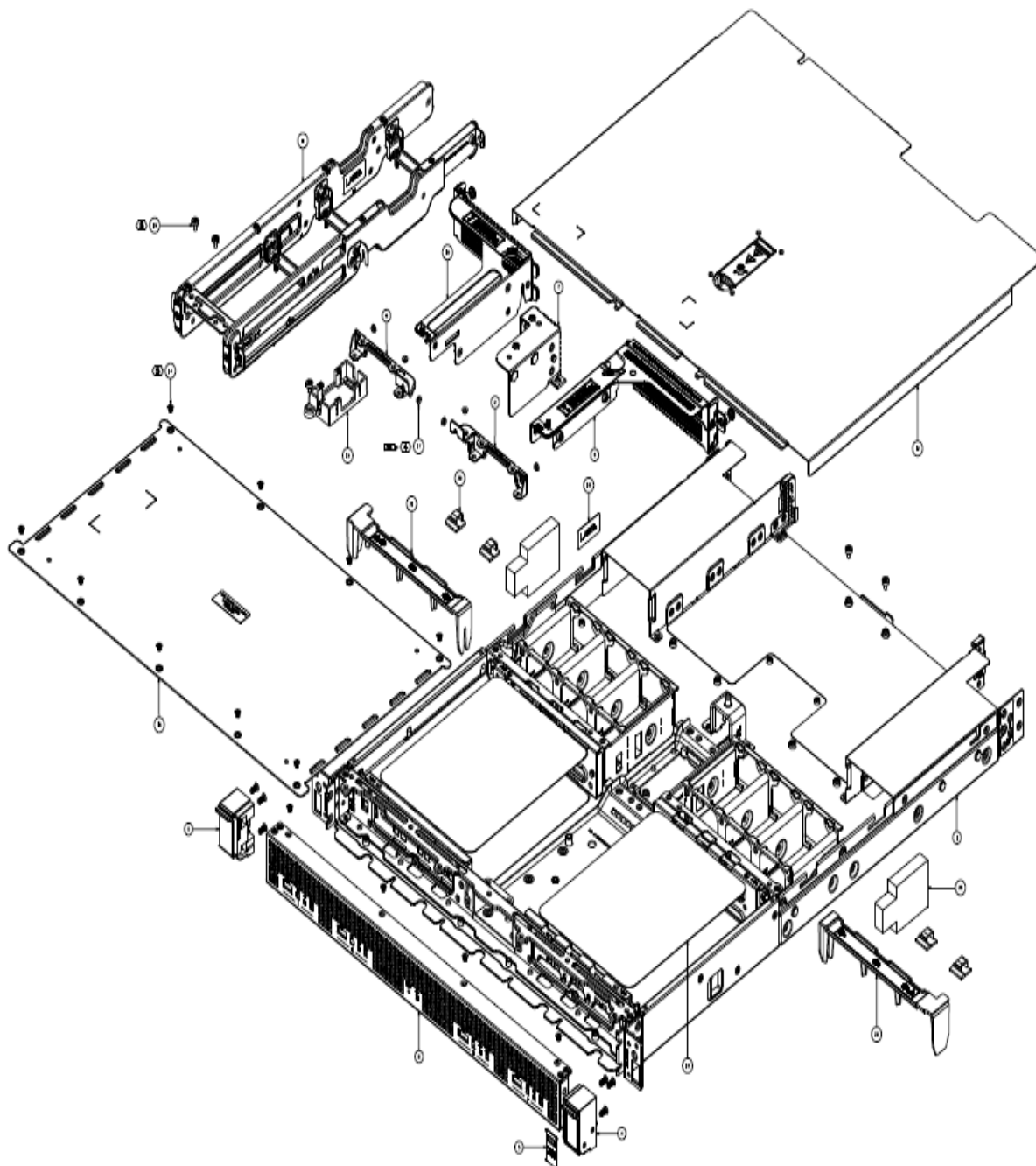
**Attachment 2 – Remove Mainboard**

**Attachment 3 – System battery location**

**Attachment 4 – Remove PSU**

**Attachment 5 –800W PSU capacitor location**

**Attachment 1 – System exploding drawing**  
**System exploding drawing**

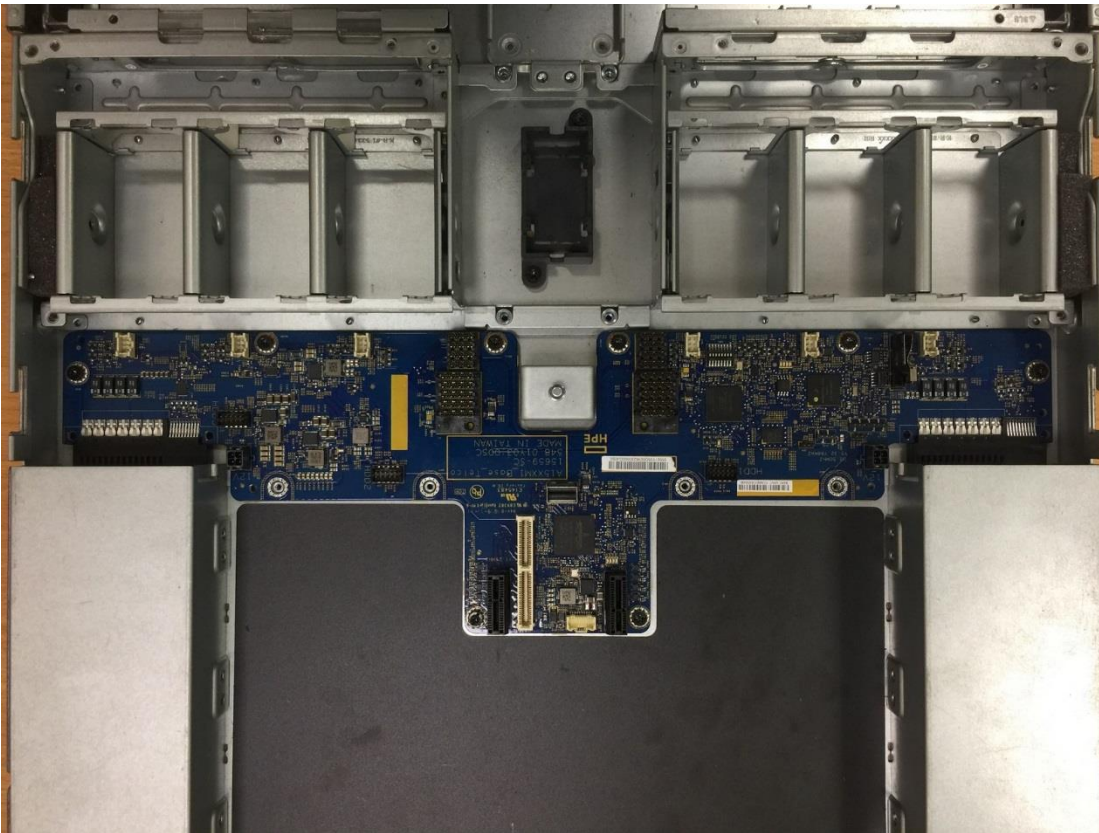


## Attachment 2 - Remove the main board

MF877-00  
Template Revision A

Page 3

HPE instructions for this template are available at [MF877-01](#)

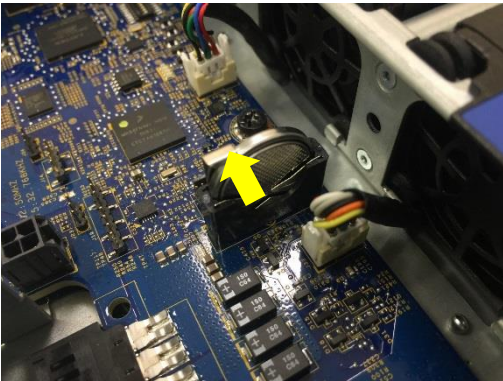
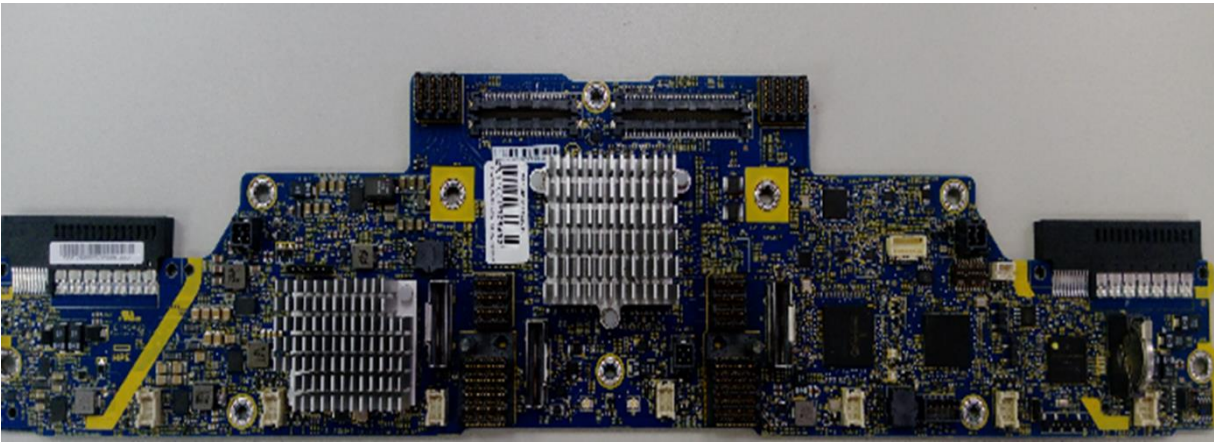


Loosen the main board by T15 screw driver (totally 8pcs as red mark show). Take out the main board to remove from chassis after loosening screws

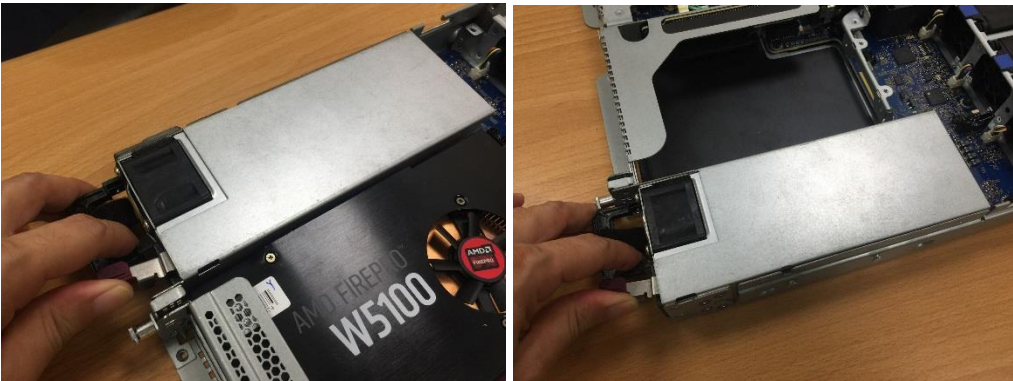
**Attachment 3 – System battery location**  
**System Battery Location**

MF877-00  
Template Revision A





**Attachment 4 – Remove PSU**

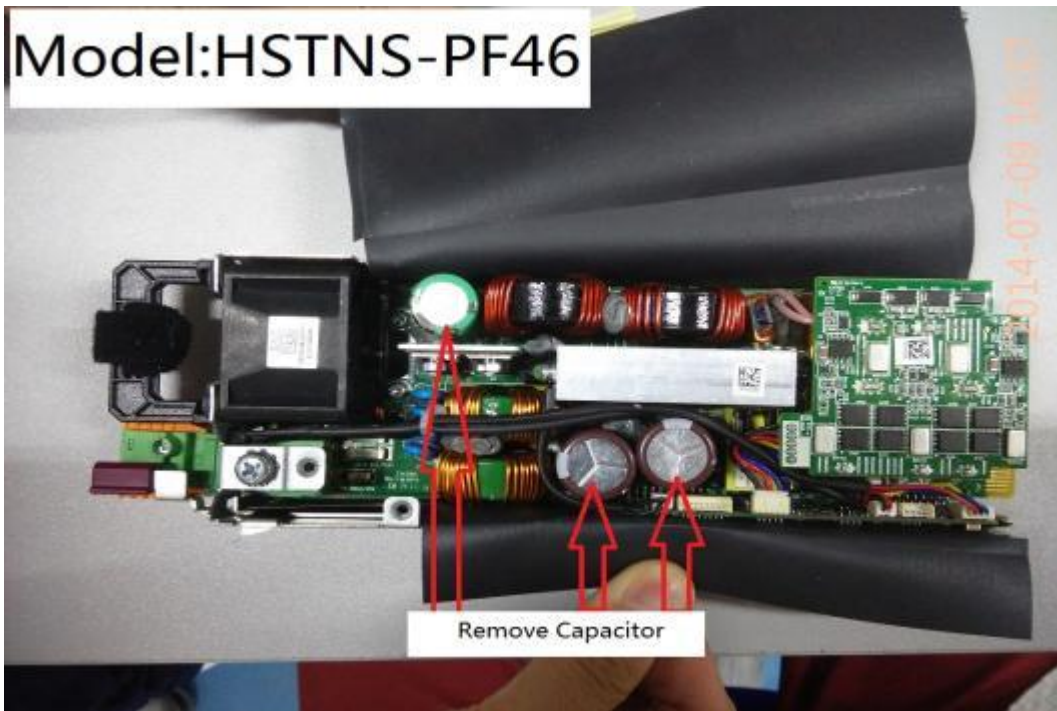


Press the latch on PSU module and pull-out the PSU module

**Attachment 5 –800W PSU capacitor location**  
**800W PSU capacitor location**

MF877-00  
Template Revision A

## 1. Remove Caps



**Model: HSTNS-PL41**  
**Remove capacitor**



**Model: HSTNS-PD41**  
**Remove capacitor**